

## N-Channel Enhancement Mode MOSFET

### GENERAL DESCRIPTION

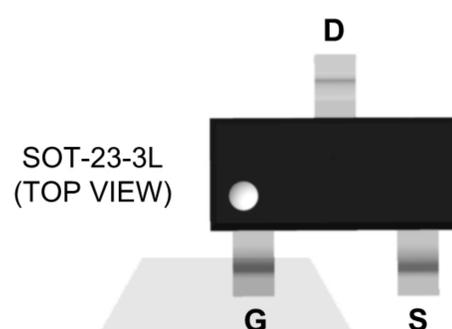
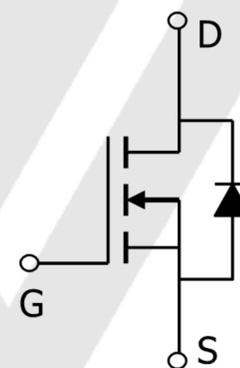
The PW2324 uses advanced trench technology to provide excellent RDS(ON), low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

### FEATURES

VDS =100V, ID =3.7A  
 RDS(ON) < 240mΩ @ VGS=10V  
 Available in a 3-Pin SOT23-3 Package

### Application

Battery protection  
 Load switch  
 Uninterruptible power supply



### Absolute Maximum Ratings (TA=25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V <sub>DS</sub>	100	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Continuous Drain Current	I <sub>D</sub> @TA=25°C	3.8	A
	I <sub>D</sub> @TA=100°C	2	
Pulsed Drain Current (NOTE1)	I <sub>DM</sub>	8	A
Power Dissipation	P <sub>D</sub> @TA=25°C	3.76	W
Power Dissipation – Derate above 25°C	P <sub>DD</sub>	0.5	W/°C
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 To 150	°C
Thermal Resistance Junction-Ambient	R <sub>θJA</sub> (MAX)	70	°C/W
Thermal Resistance Junction-Case	R <sub>θJC</sub> (MAX)	30	°C/W

Note 1、 Repetitive Rating : Pulsed width limited by maximum junction temperature.

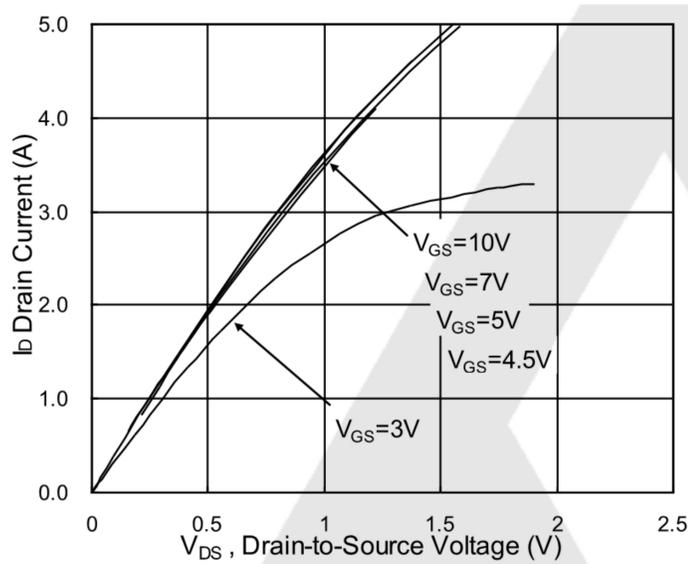
## ELECTRICAL CHARACTERISTICS

(TA = 25°C, unless otherwise noted.)

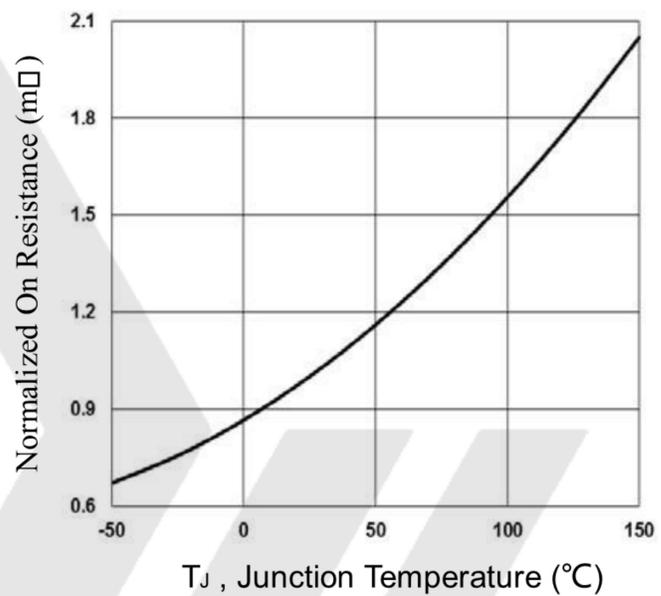
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =-250uA	100			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =-1mA		0.09		V/°C
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =10V , I <sub>D</sub> =1A		210	240	mΩ
		V <sub>GS</sub> =4.5V , I <sub>D</sub> =0.5A		240	280	mΩ
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250uA	1.0	1.9	2.5	V
$\Delta V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient			-5		mV/°C
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =100V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C			1	uA
		V <sub>DS</sub> =80V , V <sub>GS</sub> =0V , T <sub>J</sub> =125°C			10	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V , V <sub>DS</sub> =0V			±100	nA
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =10V , I <sub>D</sub> =2A		2.3		S
R <sub>g</sub>	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		2.8	5.6	Ω
Q <sub>g</sub>	Total Gate Charge (NOTE1)	V <sub>DS</sub> =50V , V <sub>GS</sub> =10V , I <sub>D</sub> =1A		9	18	nC
Q <sub>gs</sub>	Gate-Source Charge (NOTE1)			2.3	4.6	nC
Q <sub>gd</sub>	Gate-Drain Charge (NOTE1)			1.1	2.5	nC
T <sub>d(on)</sub>	Turn-On Delay Time (NOTE1)	V <sub>DS</sub> =50V , V <sub>GS</sub> =10V , R <sub>G</sub> =3.3Ω , I <sub>D</sub> =1A		5.2	10	ns
T <sub>r</sub>	Rise Time (NOTE1)			6.8	12	ns
T <sub>d(off)</sub>	Turn-Off Delay Time (NOTE1)			14.5	28	ns
T <sub>f</sub>	Fall Time (NOTE1)			2.1	5	ns
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =25V , V <sub>GS</sub> =0V , f=1MHz		152	200	pF
C <sub>oss</sub>	Output Capacitance			17	20	pF
C <sub>rss</sub>	Reverse Transfer Capacitance			10	15	pF
I <sub>S</sub>	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			4	A
I <sub>SM</sub>	Pulsed Source Current				8	A
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V , I <sub>S</sub> =1A , T <sub>J</sub> =25°C			1	V

Note 1. Essentially independent of operating temperature. The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$ . Note

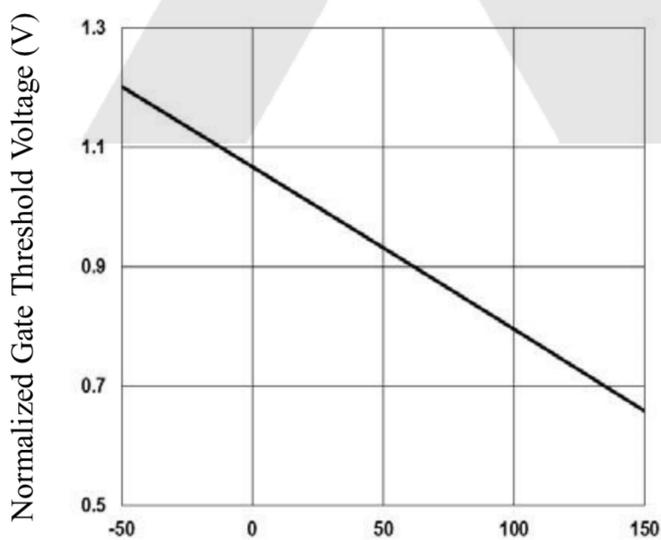
## Thermal Characteristics And Typical electrical



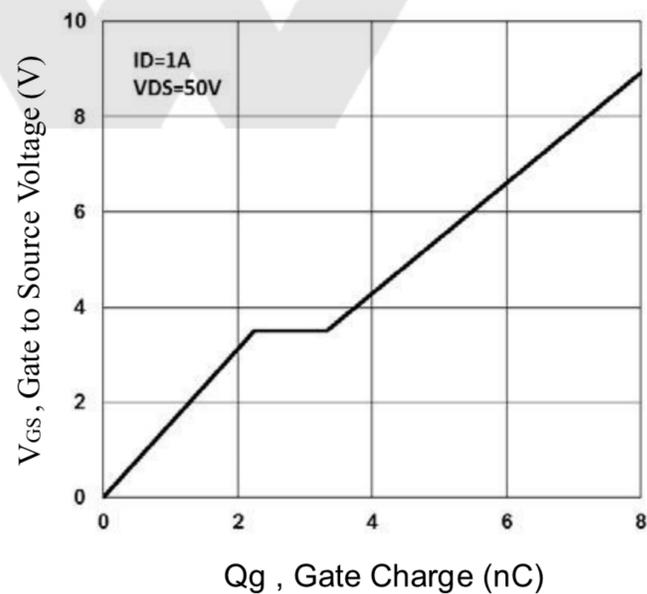
Typical Output Characteristics



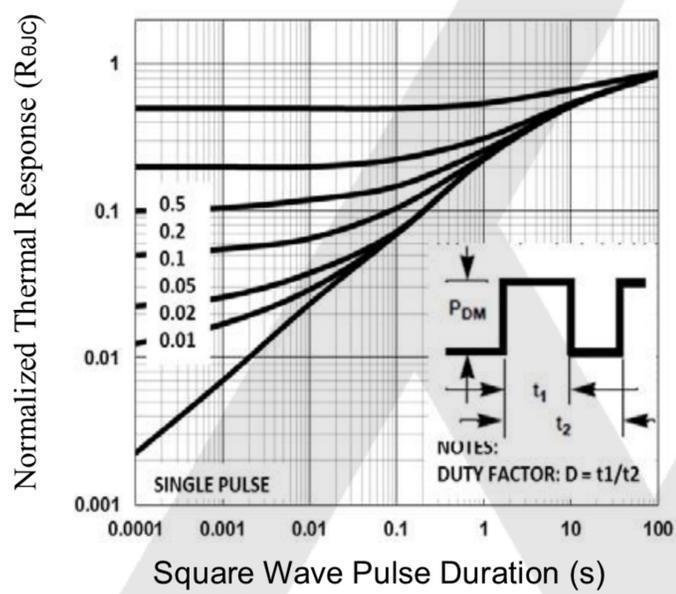
Normalized  $R_{DS(on)}$  vs.  $T_J$



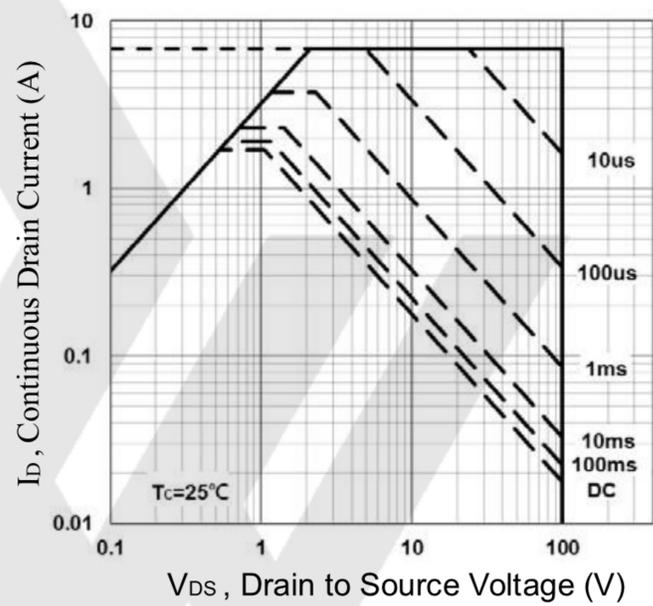
Normalized  $V_{th}$  vs.  $T_J$



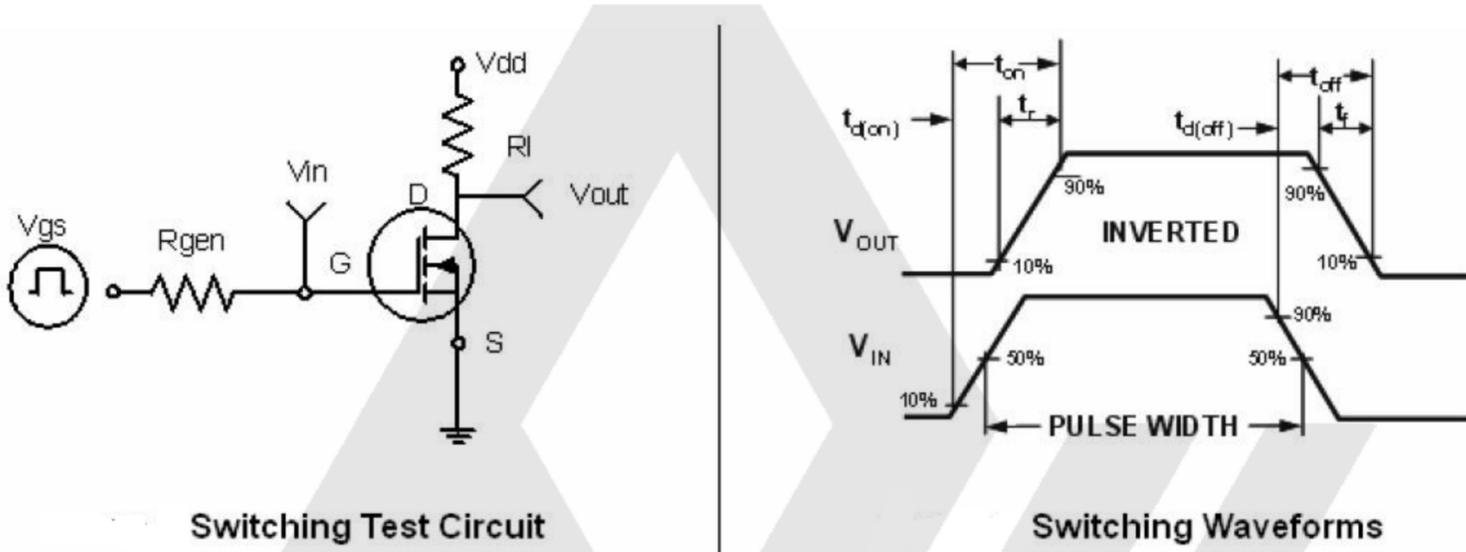
Gate Charge Waveform



Normalized Transient Impedance

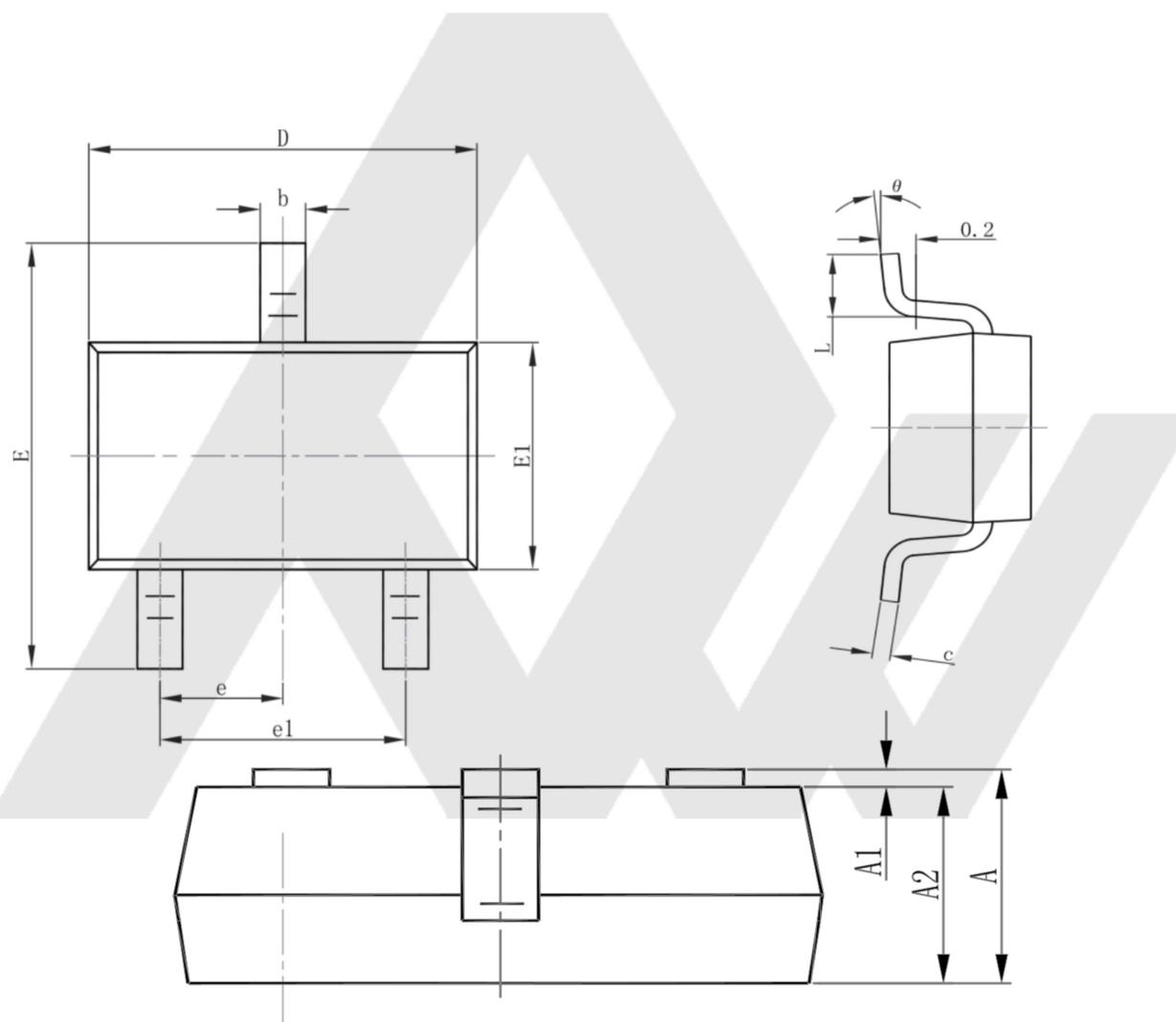


Maximum Safe Operation Area



## PACKAGE DESCRIPTION

### SOT23-3L



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E1	1.500	1.700	0.059	0.067
E	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
$\theta$	0°	8°	0°	8°

### Notes

1. All dimensions are in millimeters.
2. Tolerance  $\pm 0.10\text{mm}$  (4 mil) unless otherwise specified
3. Package body sizes exclude mold flash and gate burrs. Mold flash at the non-lead sides should be less than 5 mils.
4. Dimension L is measured in gauge plane.
5. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.

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